

Date	User	Film	Recipe	Substrate	Coat		Thickness	JAW EC-400		Avg Index	Index+1%	Index-1%	Dep.rate	Avg.Dep.		Avg+3%	Avg-3%	HF e.r.	Stress	Avg			LPD (light point defects)		Comment	Mile Silva
					time	Dep.time		Index @ 632.8nm	Index @ 1550nm					Rate	Rate					Stress	Avg+50%	Avg-50%	before dep.	after dep.		
300°C min sec (Å)																										
Index @ 632.8nm Index @ 1550nm (nm/min) (nm/min) (nm/min) (nm/min) (nm/min) MPa																										
before dep. after dep. 4"Si wafer, placed in the center of platen Mike Silva																										
LS Nitride 2																										
01/17/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2489.91	1.932	1.899	1.932	1.951	1.913	8.30	8.34	8.59	8.09	45.13	-0.99	-45.54	-68.31	-22.77	59	294	New recipe		
01/30/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2533.04	1.933	1.899	1.932	1.951	1.913	8.44	8.34	8.59	8.09			-45.54	-68.31	-22.77			Film less uniform		
02/03/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2437.59	1.932	1.899	1.932	1.951	1.913	8.13	8.34	8.59	8.09	43.75	-19.07	-45.54	-68.31	-22.77	104	437	Film OK		
02/18/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2469.99	1.931	1.898	1.932	1.951	1.913	8.23	8.34	8.59	8.09	41.27	-57.04	-45.54	-68.31	-22.77	15	74	Film less uniform	2/14/14 Silane change	
03/12/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2544.75	1.932	1.898	1.932	1.951	1.913	8.48	8.34	8.59	8.09	54.74	-28.14	-45.54	-68.31	-22.77	56	99	Film OK		
04/13/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2529.82	1.931	1.896	1.932	1.951	1.913	8.43	8.34	8.59	8.09	43.40	-122.46	-45.54	-68.31	-22.77	49	161	Film OK		

Avg. Thickness	2500.85	Avg Dep.Rate	8.34	Avg HF e.r	45.66
Avg. Index	1.932	Avg+3%	8.59	Avg Stress	-45.54
Index+1%	1.951	Avg-3%	8.09	Avg+50%	-68.31
Index-1%	1.913			Avg-50%	-22.77

